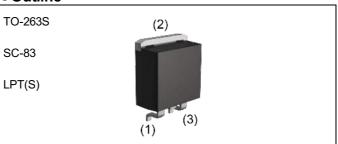


RCJ451N20

Nch 200V 45A Power MOSFET

V_{DSS}	200V
R _{DS(on)} (Max.)	55mΩ
l _D	±45A
P _D	211W

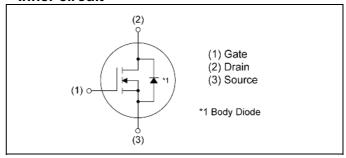
Outline



Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) Drive circuits can be simple
- 4) Parallel use is easy
- 5) Pb-free plating; RoHS compliant
- 6) 100% Avalanche tested

•Inner circuit



Packaging specifications

♥ i ackaţ	Jing specifications	
	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	24
	Quantity (pcs)	1000
	Taping code	TL
	Marking	RCJ451N20

Application

Switching

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

Paramete	Symbol	Value	Unit	
Drain - Source voltage	V_{DSS}	200	V	
0	T _c = 25°C	I _D *1	±45	Α
Continuous drain current	T _c = 100°C	I _D	±24.4	Α
Pulsed drain current		I _{DP} *2	180	Α
Gate - Source voltage	V _{GSS}	±30	V	
Avalanche energy, single pulse		E _{AS} *3	160	mJ
Avalanche current, repetitive		I _{AR} *3	22.5	А
Dower discipation	T _c = 25°C	P _D	211	W
Power dissipation $T_a = 25^{\circ}C$		P _D *4	1.56	W
Junction temperature		T _j	150	°C
Operating junction and storage temperature range		T _{stg}	-55 to +150	°C

●Thermal resistance

Doromotor	Symbol	Values			Lloit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R _{thJC}	-	-	0.59	°C/W
Thermal resistance, junction - ambient	R _{thJA}	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T _{sold}	-	-	265	°C

● Electrical characteristics (T_a = 25°C)

Darameter	Cymah al	Conditions	Values			Unit	
Parameter	Symbol Conditions —		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		200	-	-	V	
		V _{DS} = 200V, V _{GS} = 0V					
Zero gate voltage drain current	I _{DSS}	$T_j = 25^{\circ}C$		-	10	μΑ	
		$T_j = 125^{\circ}C$	-	-	-		
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 30V$, $V_{DS} = 0V$	1	1	±100	nA	
Gate threshold voltage V _{GS(th)}		V_{DS} = 10V, I_D = 1mA	3.0	1	5.0	V	
		$V_{GS} = 10V, I_D = 22.5A$	Ī	42	55		
Static drain - source on - state resistance	R _{DS(on)} *5	$V_{GS} = 10V, I_D = 22.5A$ $T_j = 125^{\circ}C$	-	95	125	mΩ	
Forward Transfer Admittance	Y _{fs} *5	V _{DS} = 10V, I _D = 22.5A	10	20	-	S	

^{*1} Limited only by maximum temperature allowed.

^{*2} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*3} L \simeq 500 μ H, V_{DD} = 50V, R_G = 25 Ω , starting T_j = 25 $^{\circ}$ C

^{*4} Mounted on a epoxy PCB FR4 (25mm×27mm×0.8mm)

^{*5} Pulsed

● Electrical characteristics (T_a = 25°C)

Darameter	Cymah al	Conditions	Values			Unit	
Parameter	Symbol Conditions —		Min.	Тур.	Max.	Unit	
Input capacitance	C _{iss}	V _{GS} = 0V	-	4200	-		
Output capacitance	C _{oss}	V _{DS} = 25V	-	270	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	160	-		
Turn - on delay time	$t_{d(on)}^{*5}$	$V_{DD} \simeq 100V$, $V_{GS} = 10V$	-	52	1		
Rise time	t _r *5	I _D = 22.5A	-	210	1	no	
Turn - off delay time	t _{d(off)} *5	$R_L \simeq 4.4\Omega$	-	90	-	ns	
Fall time	t _f *5	$R_G = 10\Omega$	-	70	-		

● Gate charge characteristics (T_a = 25°C)

Darameter	Symbol Conditions —		Values			Lloit
Parameter			Min.	Тур.	Max.	Unit
Total gate charge	Q_g^{*5}	V _{DD} ≈ 100V	-	80	-	
Gate - Source charge	Q _{gs} *5	I _D = 45A	-	28	-	nC
Gate - Drain charge	Q _{gd} *5	V _{GS} = 10V	-	28	-	
Gate plateau voltage	V _(plateau)	V _{DD} ≈ 100V, I _D = 45A	-	7.2	-	V

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit	
Farameter	Symbol Conditions		Min.	Тур.	Max.	UIIIL	
Continuous forward current	I _S *1	T- = 25°C	1	1	45	Α	
Pulse forward current	I _{SP} *2	T _C = 25°C	1	1	180	Α	
Forward voltage	V _{SD} *5	$V_{GS} = 0V, I_{S} = 45A$	ı	ı	1.5	٧	
Reverse recovery time	t _{rr} *5	I _S = 45A	-	130	-	ns	
Reverse recovery charge	Q _{rr} *5	di/dt = 100A/µs	-	600	-	nC	

Fig.1 Power Dissipation Derating Curve

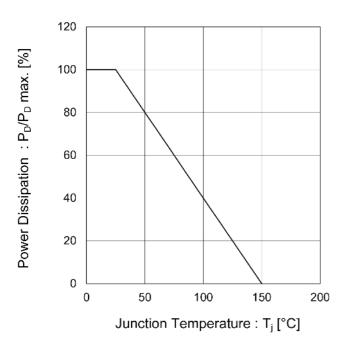
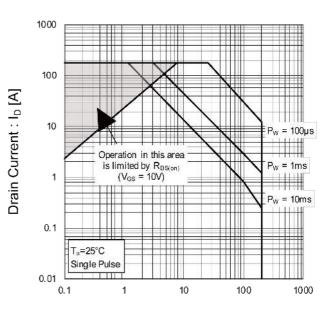


Fig.2 Maximum Safe Operating Area



Drain - Source Voltage: V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

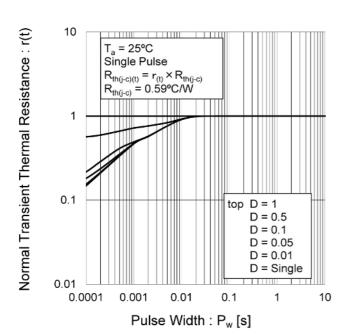


Fig.4 Avalanche Current vs. Inductive Load

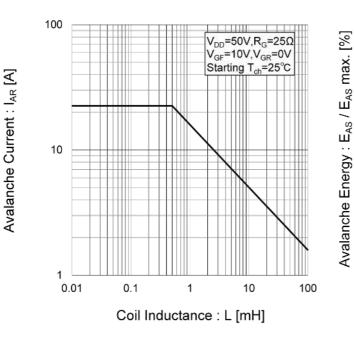


Fig.5 Avalanche Energy Derating Curve vs. Junction Temperature

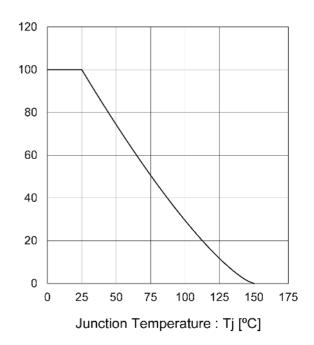


Fig.6 Typical Output Characteristics(I)

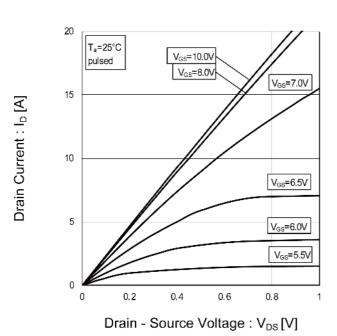
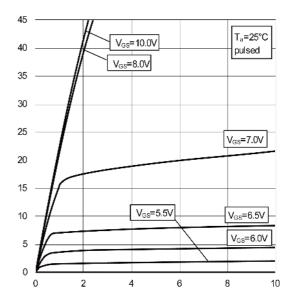


Fig.7 Typical Output Characteristics(II)



Drain - Source Voltage : V_{DS} [V]

Drain Current: I_D [A]

Fig.8 Breakdown Voltage vs. Junction Temperature

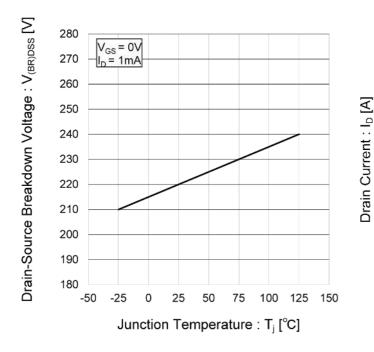
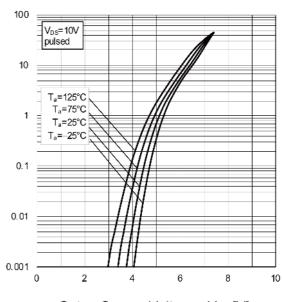


Fig.9 Typical Transfer Characteristics



Gate - Source Voltage : $V_{GS}[V]$

Fig.10 Gate Threshold Voltage vs. Junction Temperature

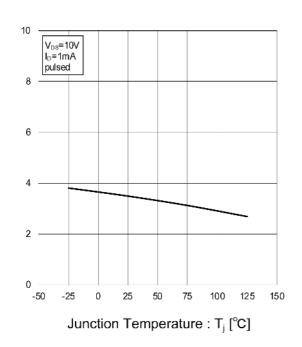
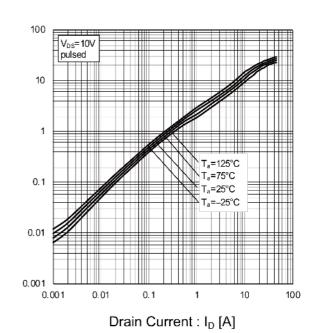


Fig.11 Transconductance vs. Drain Current



Gate Threshold Voltage: V_{GS(th)} [V]

Transconductance : g_{fs} [S]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

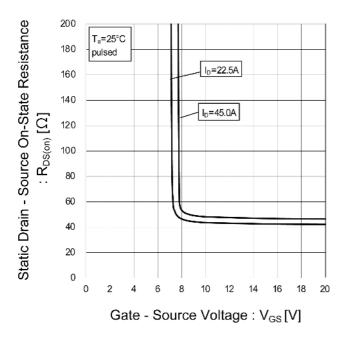


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

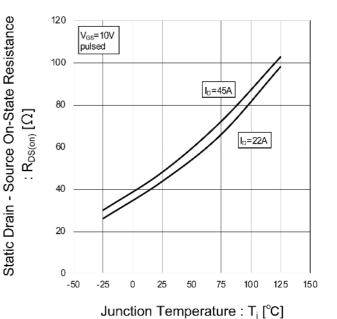




Fig.14 Static Drain - Source On - State Resistance vs. Drain Current

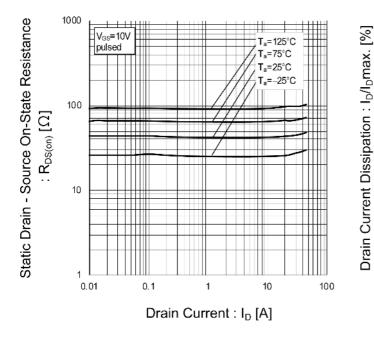


Fig.15 Drain Current Derating Curve

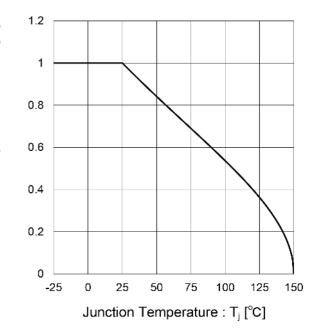
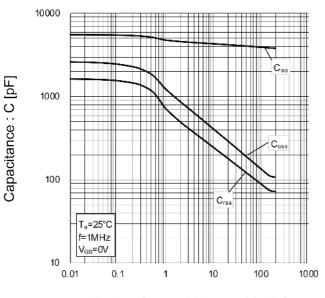




Fig.16 Typical Capacitance vs. Drain - Source Voltage



Drain - Source Voltage : VDS [V]

Fig.17 Switching Characteristics

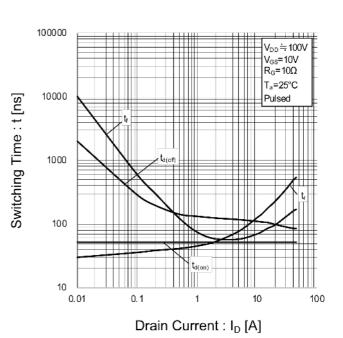
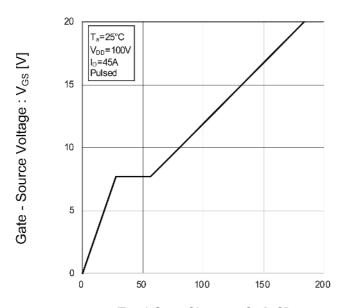


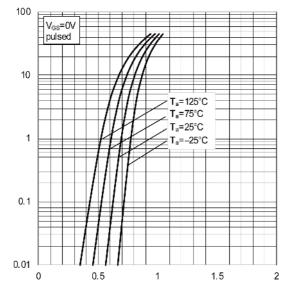
Fig.18 Dynamic Input Characteristics



Total Gate Charge : Q_g [nC]

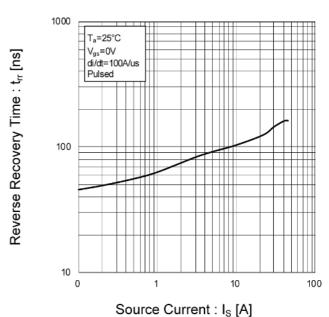
Source Current: Is [A]

Fig.19 Source Current vs. Source-Drain Voltage



Source - Drain Voltage : V_{SD} [V]

Fig.20 Reverse Recovery Time vs. Source Current



Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

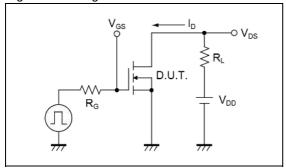


Fig.2-1 Gate Charge Measurement Circuit

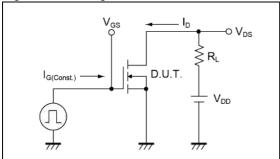


Fig.3-1 Avalanche Measurement Circuit

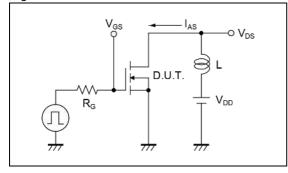


Fig.1-2 Switching Waveforms

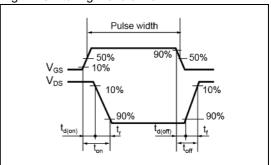


Fig.2-2 Gate Charge Waveform

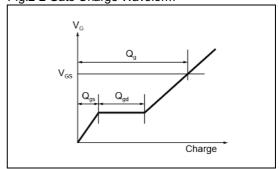
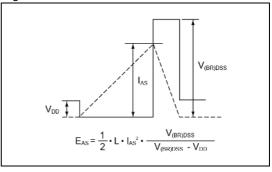
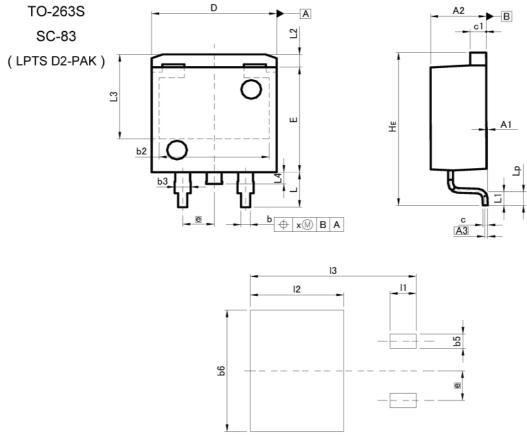


Fig.3-2 Avalanche Waveform



Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.30	0.000	0.012
A2	4.30	4.70	0.169	0.185
A3	0.	25	0.0	10
b	0.68	0.98	0.027	0.039
b2	8.	90	0.3	50
ь3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.	54	0.1	00
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.130
L1	1.	20	0.047	
L2	1.	10	0.043	
L3	7.25		0.2	85
L4	1.	00	0.0	39
Lp	0.90	1.50	0.035	0.059
Х	<i>=1</i>	0.25	-	0.010
	NATI TNA	-TEDO	INC	

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
bb	H.:	1.23	-	0.049
b6		10.40	_	0.409
11	227	2.10	, 12	0.083
12		7.55	-	0.297
13	-	13.40	-	0.528

Dimension in mm/inches

Notice

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CLASSIV	CLASSII	CLASSⅢ	CLASSⅢ

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 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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